

1     **ABSTRACT OF THE DISCLOSURE**

2             In one aspect, the invention includes a method of encapsulating  
3     a semiconductor device, comprising: a) providing a semiconductor device;  
4     b) providing a dispensing apparatus having a plurality of dispensing  
5     orifices proximate the semiconductor device; and c) dispensing a liquid  
6     encapsulating material through the plurality of orifices and over the  
7     semiconductor device. In another aspect, the invention includes a  
8     method of forming an electronic package, comprising: a) providing a  
9     circuit board having a circuit pattern; b) joining a plurality of  
10    semiconductor devices to the circuit board in electrical connection with  
11    the circuit pattern; c) providing a dispensing apparatus having a plurality  
12    of dispensing orifices proximate the semiconductor devices; d)  
13    simultaneously dispensing liquid encapsulating material through at least  
14    two of the plurality of orifices and over at least two of the  
15    semiconductor devices; and e) curing the liquid encapsulating material.

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